



N-Ch 30V Fast Switching MOSFETs

- ★ Green Device Available
- ★ Super Low Gate Charge
- ★ Excellent CdV/dt effect decline
- ★ Advanced high cell density Trench technology

Product Summary



BVDSS

RDSON

ID

30V

8.5 mΩ

13 A

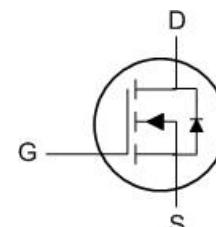
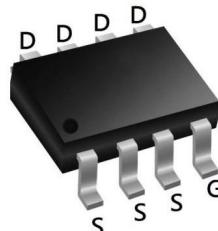
Description

The FDS6690A-NL is the high cell density trenched N-ch MOSFETs, which provide excellent RDSON and gate charge for most of the synchronous buck converter applications.

The FDS6690A-NL meet the RoHS and Green Product requirement, 100% EAS guaranteed with full function reliability approved.

Marking:4406

SOP8 Pin Configuration



Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	30	V
V_{GS}	Gate-Source Voltage	± 20	V
$I_D @ T_A = 25^\circ C$	Continuous Drain Current, $V_{GS} @ 10V^1$	13	A
$I_D @ T_A = 70^\circ C$	Continuous Drain Current, $V_{GS} @ 10V^1$	7.6	A
I_{DM}	Pulsed Drain Current ²	55	A
EAS	Single Pulse Avalanche Energy ³	33	mJ
I_{AS}	Avalanche Current	20	A
$P_D @ T_A = 25^\circ C$	Total Power Dissipation ⁴	5	W
T_{STG}	Storage Temperature Range	-55 to 150	°C
T_J	Operating Junction Temperature Range	-55 to 150	°C

Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction-ambient ¹	---	85	°C/W
$R_{\theta JC}$	Thermal Resistance Junction-Case ¹	---	25	°C/W



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Electrical Characteristics ($T_J=25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Units
Off Characteristic						
$V_{(\text{BR})\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}$, $I_D=250\mu\text{A}$	30	-	-	V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{\text{DS}}=30\text{V}$, $V_{\text{GS}}=0\text{V}$,	-	-	1.0	μA
I_{GSS}	Gate to Body Leakage Current	$V_{\text{DS}}=0\text{V}$, $V_{\text{GS}}=\pm 20\text{V}$	-	-	± 100	nA
On Characteristics						
$V_{\text{GS}(\text{th})}$	Gate Threshold Voltage	$V_{\text{DS}}=V_{\text{GS}}$, $I_D=250\mu\text{A}$	1.0	1.5	2.5	V
$R_{\text{DS}(\text{on})}$ note3	Static Drain-Source on-Resistance	$V_{\text{GS}}=10\text{V}$, $I_D=13\text{A}$	-	8.5	12	$\text{m}\Omega$
		$V_{\text{GS}}=4.5\text{V}$, $I_D=10\text{A}$	-	13	18	
Dynamic Characteristics						
C_{iss}	Input Capacitance	$V_{\text{DS}}=15\text{V}$, $V_{\text{GS}}=0\text{V}$, $f=1.0\text{MHz}$	-	1011	-	pF
C_{oss}	Output Capacitance		-	142	-	pF
C_{rss}	Reverse Transfer Capacitance		-	119	-	pF
Q_g	Total Gate Charge	$V_{\text{DS}}=15\text{V}$, $I_D=6\text{A}$, $V_{\text{GS}}=10\text{V}$	-	19	-	nC
Q_{gs}	Gate-Source Charge		-	6.3	-	nC
Q_{gd}	Gate-Drain("Miller") Charge		-	4.5	-	nC
Switching Characteristics						
$t_{\text{d}(\text{on})}$	Turn-on Delay Time	$V_{\text{DS}}=15\text{V}$, $I_D=13\text{A}$, $R_{\text{GEN}}=3\Omega$, $V_{\text{GS}}=10\text{V}$	-	6	-	ns
t_r	Turn-on Rise Time		-	5	-	ns
$t_{\text{d}(\text{off})}$	Turn-off Delay Time		-	25	-	ns
t_f	Turn-off Fall Time		-	7	-	ns
Drain-Source Diode Characteristics and Maximum Ratings						
I_s	Maximum Continuous Drain to Source Diode Forward Current		-	-	13	A
I_{SM}	Maximum Pulsed Drain to Source Diode Forward Current		-	-	52	A
V_{SD}	Drain to Source Diode Forward Voltage	$V_{\text{GS}}=0\text{V}$, $I_s=13\text{A}$	-	-	1.2	V
t_{rr}	Body Diode Reverse Recovery Time	$I_F=13\text{A}$, $dI/dt=100\text{A}/\mu\text{s}$	-	7	-	ns
Q_{rr}	Body Diode Reverse Recovery Charge		-	6.3	-	nC

Notes: 1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature

2. EAS condition: $T_J=25^\circ\text{C}$, $V_{\text{GS}}=15\text{V}$, $R_G=25\Omega$, $L=0.5\text{mH}$, $I_{\text{AS}}=11.5\text{A}$

3. Pulse Test: Pulse Width $\leq 300\mu\text{s}$, Duty Cycle $\leq 0.5\%$

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Typical Performance Characteristics

Figure 1: Output Characteristics

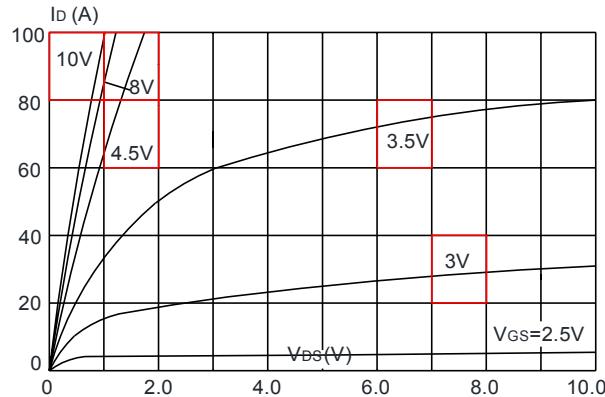


Figure 3: On-resistance vs. Drain Current

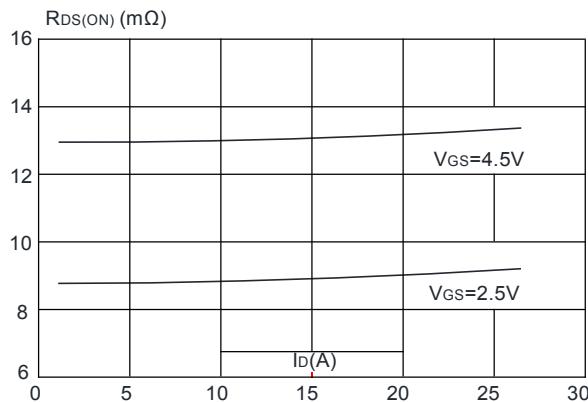


Figure 5: Gate Charge Characteristics

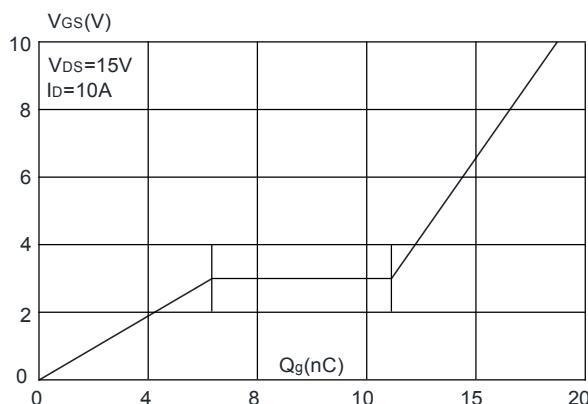


Figure 2: Typical Transfer Characteristics

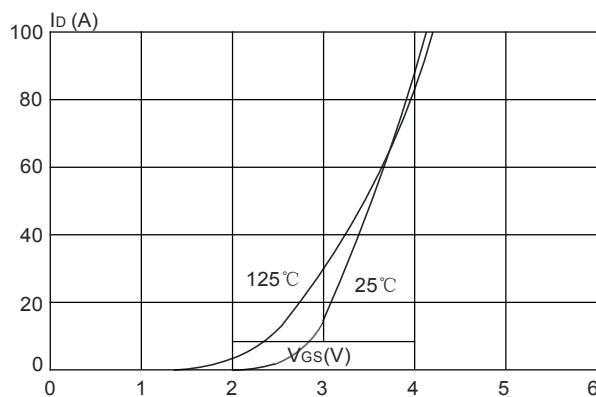


Figure 4: Body Diode Characteristics

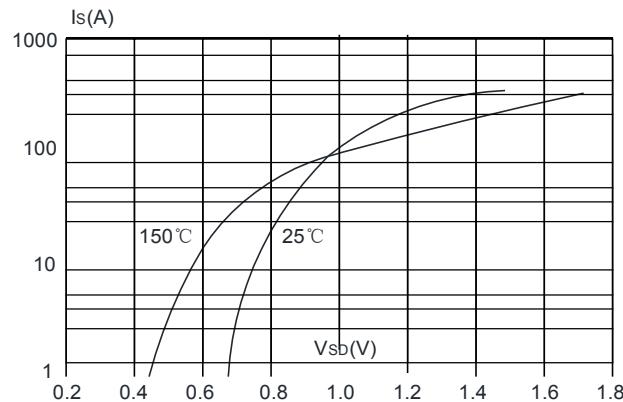


Figure 6: Capacitance Characteristics

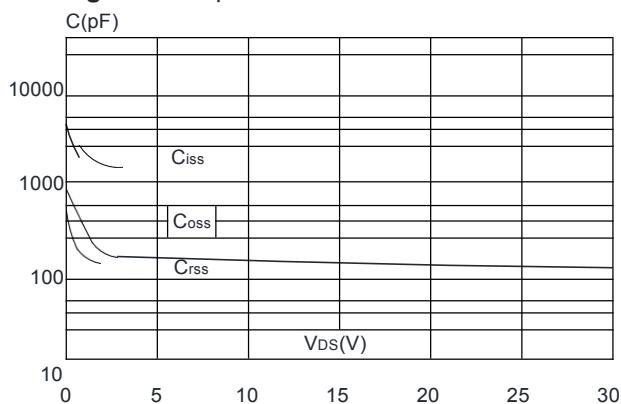




Figure 7: Normalized Breakdown Voltage vs. Junction Temperature

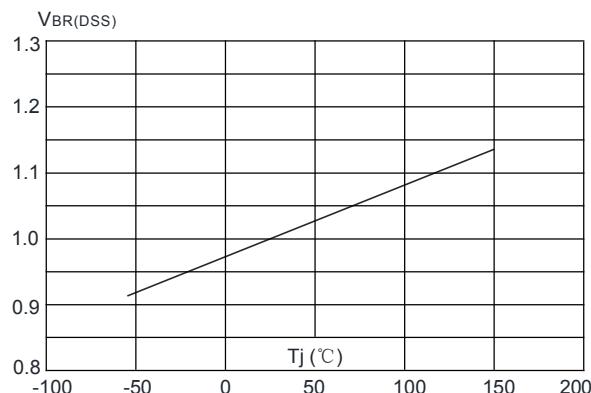


Figure 9: Maximum Safe Operating Area

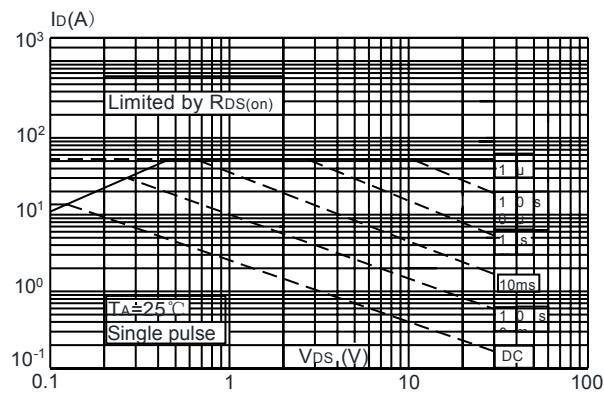
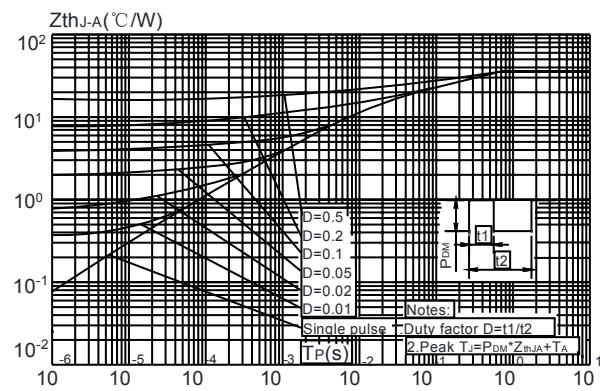


Figure 11: Maximum Effective Transient Thermal Impedance, Junction-to-Ambient



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Figure 8: Normalized on Resistance vs. Junction Temperature

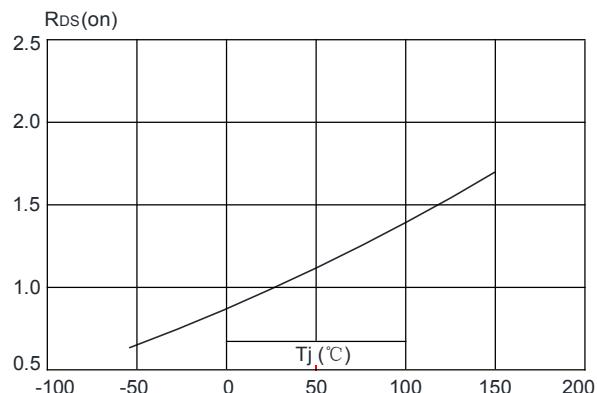
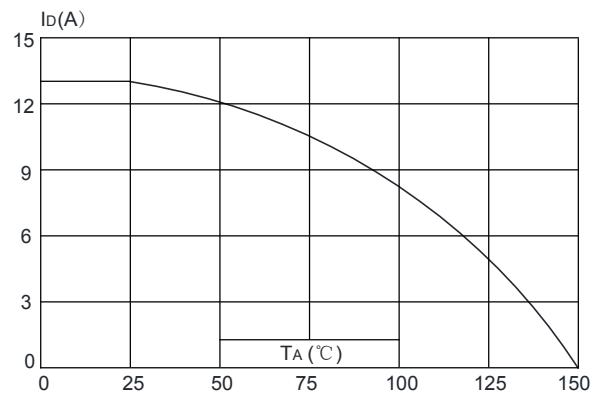


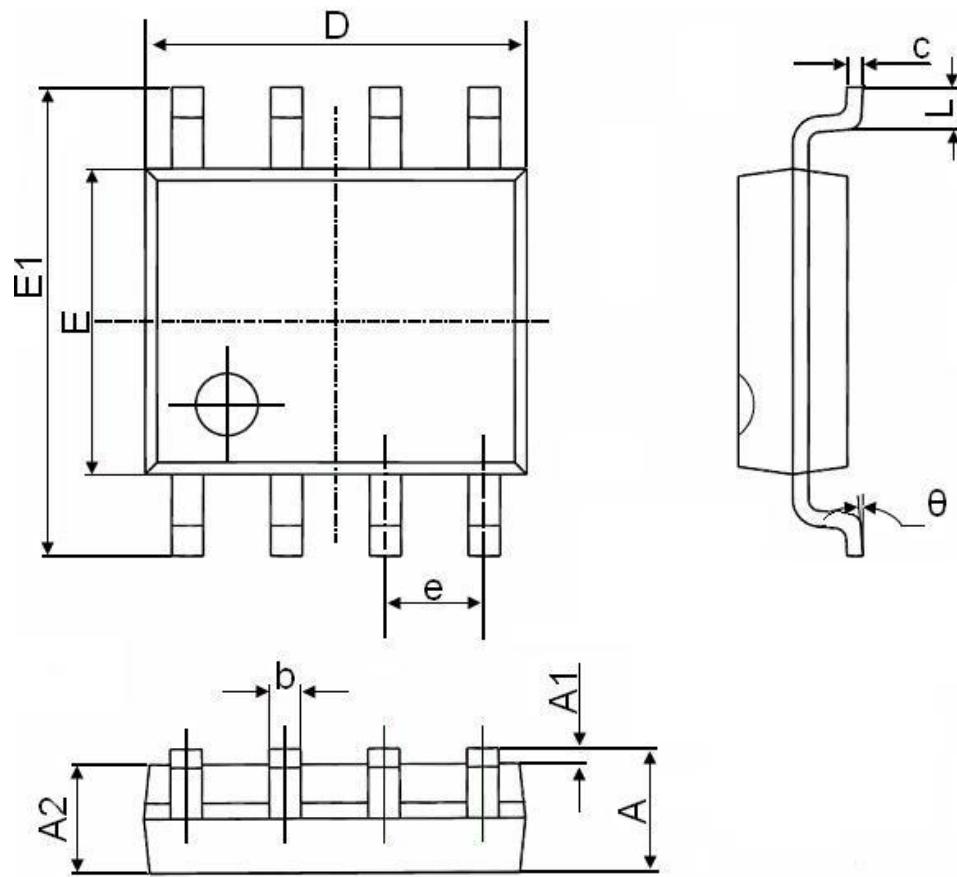
Figure 10: Maximum Continuous Drain Current vs. Ambient Temperature





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SOP-8 Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	1.350	1.750	0.053	0.069
A1	0.100	0.250	0.004	0.010
A2	1.350	1.550	0.053	0.061
b	0.330	0.510	0.013	0.020
c	0.170	0.250	0.006	0.010
D	4.700	5.100	0.185	0.200
E	3.800	4.000	0.150	0.157
E1	5.800	6.200	0.228	0.244
e	1.270(BSC)		0.050(BSC)	
L	0.400	1.270	0.016	0.050
θ	0°	8°	0°	8°